<u>S/N 10/721,722</u> <u>PATENT</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Michael O'Connor et al.

Examiner: Michael M. Trinh

Frial No.: 10/721,722

Group Art Unit: 2822

Filed: November 25, 2003

Docket No.: 884.398US2

Title: DIAMOND HEAT SPREADING AND COOLING

TECHNIQUE FOR INTEGRATED CIRCUITS

Assignee: Intel Corporation Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

This responds to the Office Action mailed on July 1, 2005. Please amend the above-identified patent application as follows.